

3A, 50V - 1000V Surface Mount Fast Recovery Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Fast switching for high efficiency
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- · Polarity: As marked
- Weight: 0.21 g (approximately)

KEY PARAMETERS						
PARAMETER	VALUE	UNIT				
I _{F(AV)}	3	Α				
V_{RRM}	50 - 1000	V				
I _{FSM}	100	Α				
T _{J MAX}	150	°C				
Package	DO-214AB (SMC					
Configuration	Single	die				





DO-214AB (SMC)

PARAMETER	SYMBOL	RS3A	RS3B	RS3D	RS3G	RS3J	RS3K	RS3M	UNIT
Marking code on the device		RS3A	RS3B	RS3D	RS3G	RS3J	RS3K	RS3M	
Repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Forward current	I _{F(AV)}				3				Α
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I _{FSM}	100			А				
Junction temperature	T _J	- 55 to +150				°C			
Storage temperature	T _{STG}	- 55 to +150				°C			



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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	TYP	UNIT			
Junction-to-lead thermal resistance per diode	$R_{\Theta JL}$	15	°C/W			
Junction-to-ambient thermal resistance per diode	R _{⊖JA}	50	°C/W			

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP.	MAX.	UNIT
Forward voltage per diode (1		I _F = 3A, T _J = 25°C	V_{F}	-	1.3	V
Doverse surrent @ reted //	nor diada ⁽²⁾	T _J = 25°C	,	-	10	μA
Reverse current @ rated v _R	current @ rated V_R per diode $^{(2)}$ $T_J =$		- I _R	-	250	μΑ
Reverse recovery time	RS3A RS3B RS3D RS3G	I _F =0.5A , I _R =1.0A	t _{rr}	-	150	ns
Treveled receivery time	RS3J	I _{RR} =0.25A	·rr	-	250	ns
	RS3K RS3M			-	500	ns

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

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ORDERING INFORMATION						
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
		R7		SMC	850 / 7" Plastic reel	
		R6		SMC	3,000 / 13" Paper reel	
RS3x (Note 1,2)	Н	M6	G	SMC	3,000 / 13" Plastic reel	
(Note 1,2)		V7		Matrix SMC	850 / 7" Plastic reel	
		V6		Matrix SMC	`3,000 / 13" Plastic reel	

Note:

- "x" defines voltage from 50V (RS3A) to 1000V (RS3M)
 Only V6 and V7 are all green compound (halogen free)

EXAMPLE						
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
RS3AHR7G	RS3A	Н	R7	G	AEC-Q101 qualified Green compound	



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

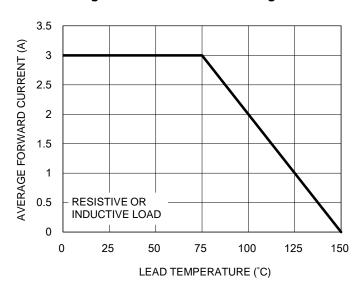


Fig.2 Typical Junction Capacitance

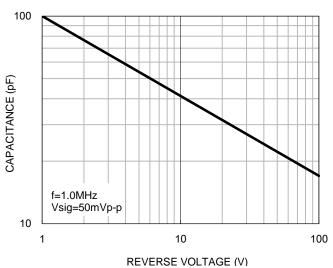


Fig.3 Typical Reverse Characteristics

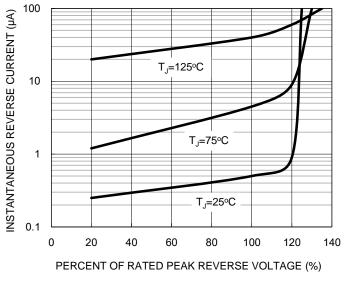
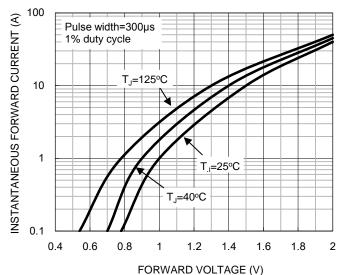


Fig.4 Typical Forward Characteristics





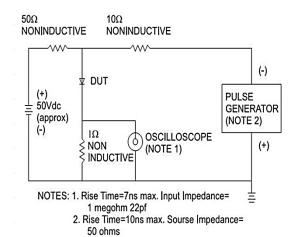
CHARACTERISTICS CURVES

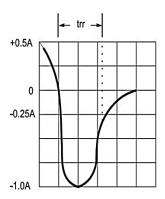
(T_A = 25°C unless otherwise noted)

Fig.5 Maximum Non-repetitive Forward Surge Current



Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram

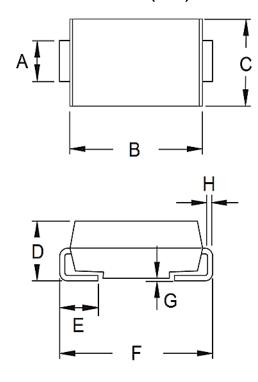






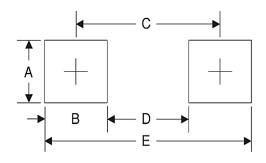
PACKAGE OUTLINE DIMENSIONS

DO-214AB (SMC)



DIM.	Unit	(mm)	Unit (inch)	
DIIVI.	Min.	Max.	Min.	Max.
Α	2.90	3.20	0.114	0.126
В	6.60	7.11	0.260	0.280
С	5.59	6.22	0.220	0.245
D	2.00	2.62	0.079	0.103
Е	1.00	1.60	0.039	0.063
F	7.75	8.13	0.305	0.320
G	0.10	0.20	0.004	0.008
Н	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
А	3.30	0.130
В	2.50	0.098
С	6.80	0.268
D	4.40	0.173
Е	9.40	0.370

MARKING DIAGRAM

Matrix SMC

SMC





P/N =Marking Code G =Green Compound

YW =Date Code F =Factory Code



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